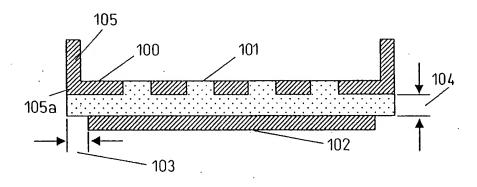
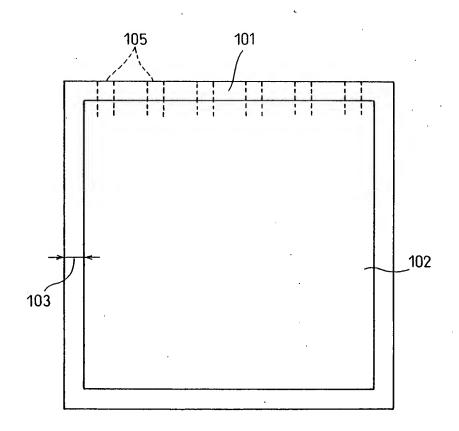


U.S. Patent Application Serial No.: 10/647,263
Docket No.: 514372000110
Confirmation No.: 2075 Group Art Unit: 2826
Title: THERMALLY CONDUCTIVE SUBSTRATE, THERMALLY
CONDUCTIVE SUBSTRATE MANUFACTURING METHOD AND
POWER MODULE
Inventors: Yoshihisa YAMASHITA, et al.
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F I G. 1

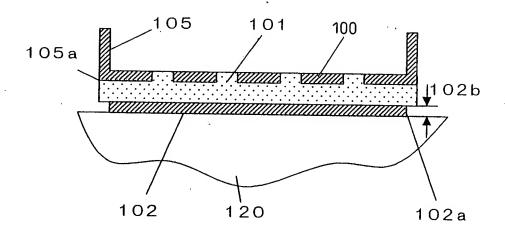


F I G. 2



U.S. Patent Application Serial No.: 10/647,263
Docket No.: 514372000110
Confirmation No.: 2075 Group Art Unit: 2826
Title: THERMALLY CONDUCTIVE SUBSTRATE, THERMALLY
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F I G. 3



U.S. Patent Application Serial No.: 10/647,263

Docket No.: 514372000110

Confirmation No.: 2075 Group Art Unit: 2826

Title: THERMALLY CONDUCTIVE SUBSTRATE, THERMALLY CONDUCTIVE SUBSTRATE MANUFACTURING METHOD AND POWER MODULE

Inventors: Yoshihisa YAMASHITA, et al.

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F I G. 4 A

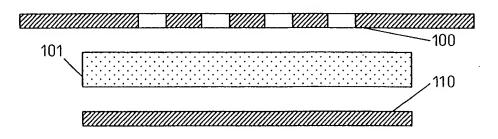


FIG.4B

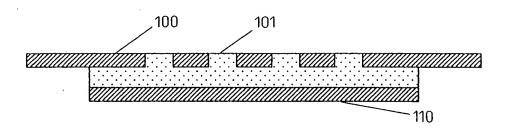
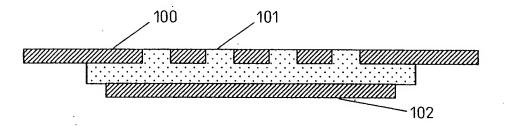


FIG. 4C



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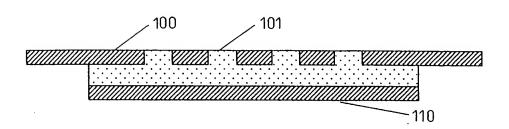
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FIG.5A



F I G. 5 B

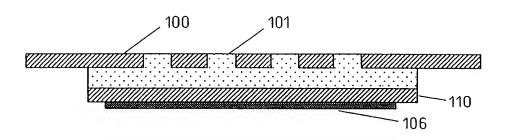
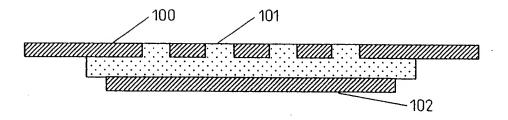


FIG.5C



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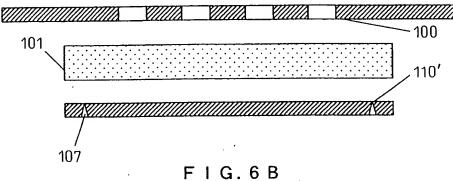
Confirmation No.: 2075 Group Art Unit: 2826

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Inventors: Yoshihisa YAMASHITA, et al.

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F I G. 6 A



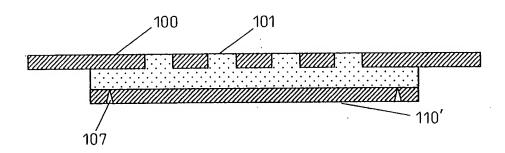
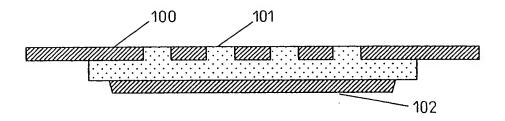
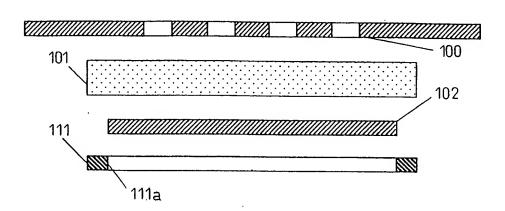


FIG.6C

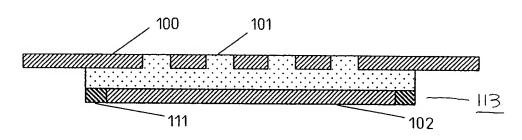


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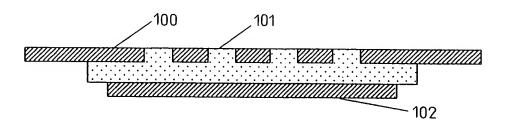
F I G. 7 A



F I G. 7 B



F I G. 7 C



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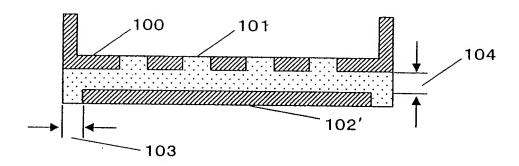
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Inventors: Yoshihisa YAMASHITA, et al.
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F I G. 8



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Inventors: Yoshihisa YAMASHITA, et al.

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F I G. 9 A

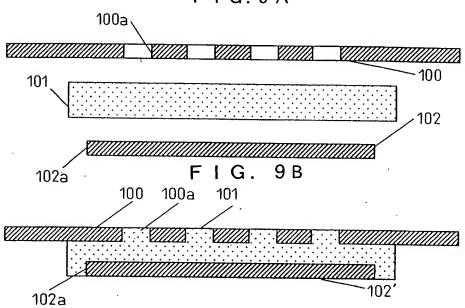
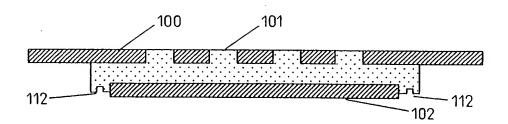
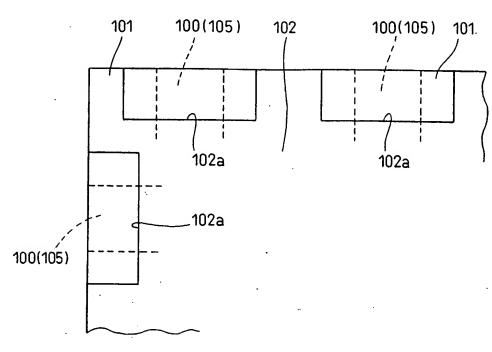


FIG. 10

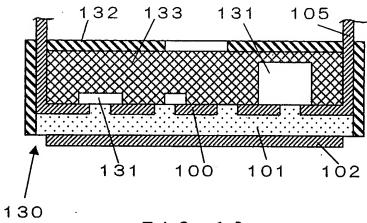


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FIG. 11



F I G. 12



F1G. 13

